



Material Content Data Sheet



Sales Product Name		IPD50N04S3-09		Issued		20. July 2018		
MA#		MA000461960						
Package		PG-TO252-3-11		Weight*		370.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.791	0.48	0.48	4839	4839
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		582	
	non noble metal	copper	7440-50-8	215.017	58.10	58.18	580894	581650
	non noble metal	aluminium	7429-90-5	1.992	0.54	0.54	5381	5381
wire	non noble metal	aluminium	7429-90-5	1.992	0.54	0.54	5381	5381
encapsulation	organic material	carbon black	1333-86-4	1.261	0.34		3406	
	plastics	epoxy resin	-	22.065	5.96		59611	
	inorganic material	silicondioxide	60676-86-0	102.758	27.76	34.06	277615	340632
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10104	10104
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.039	0.01		105	
	noble metal	silver	7440-22-4	0.049	0.01		132	
	non noble metal	lead	7439-92-1	1.863	0.50	0.52	5033	5270
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51810	51878
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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